

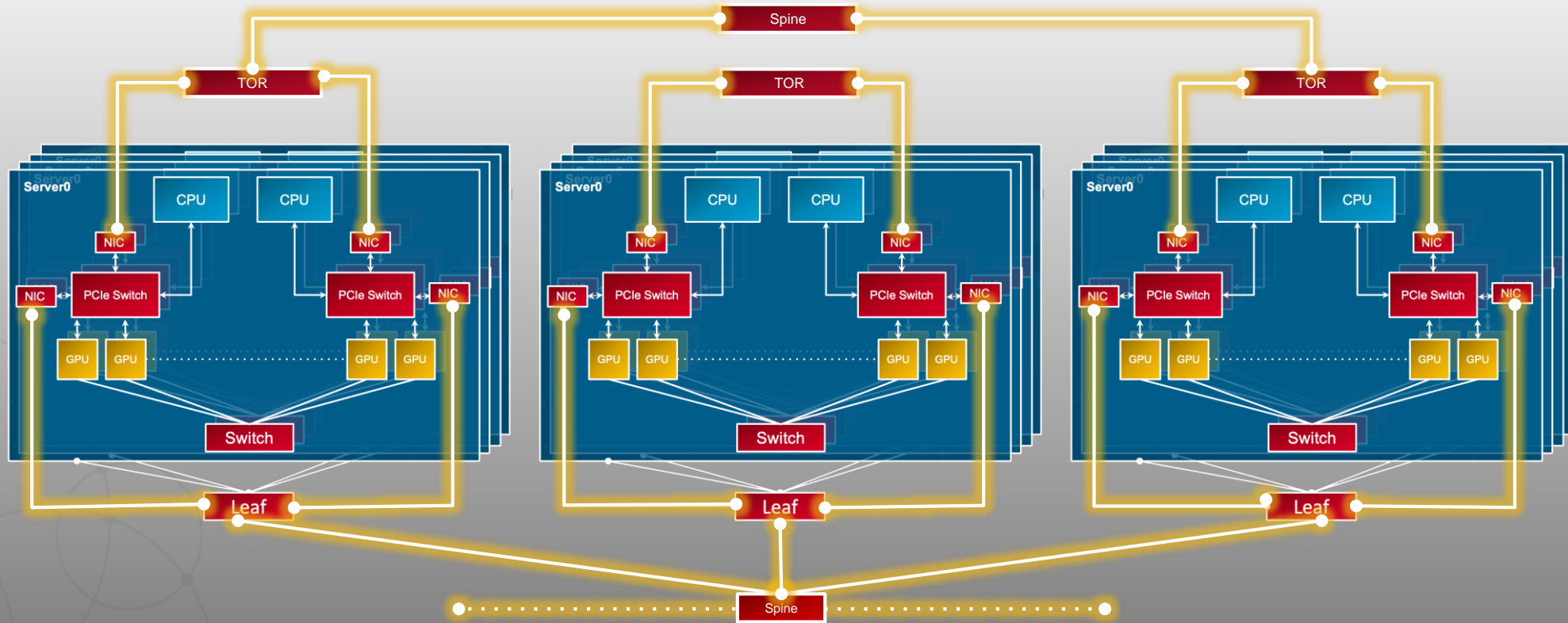


Optical Interconnects for AI: Components and Co-Packaged Optics (CPO)

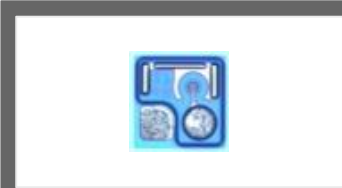
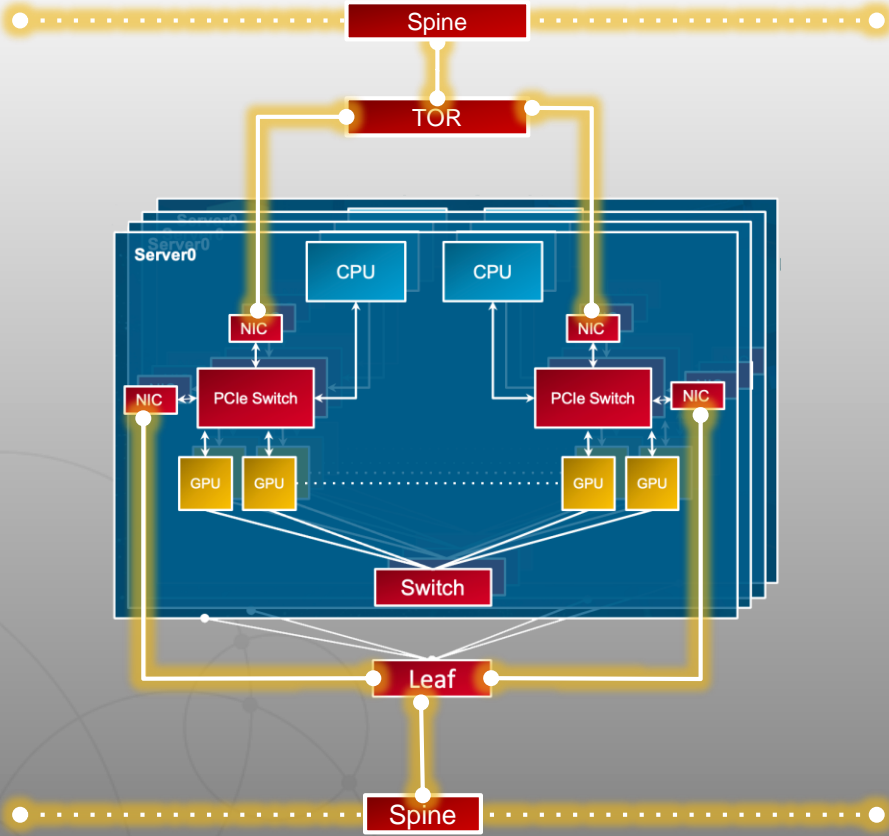
Broadcom

March 2024

The Optical Interconnect for AI

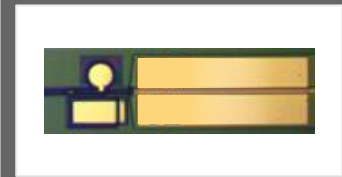


The Optical Interconnect for AI



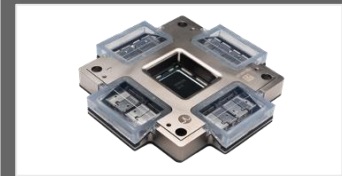
VCSEL

Multi-mode, short reach



EML

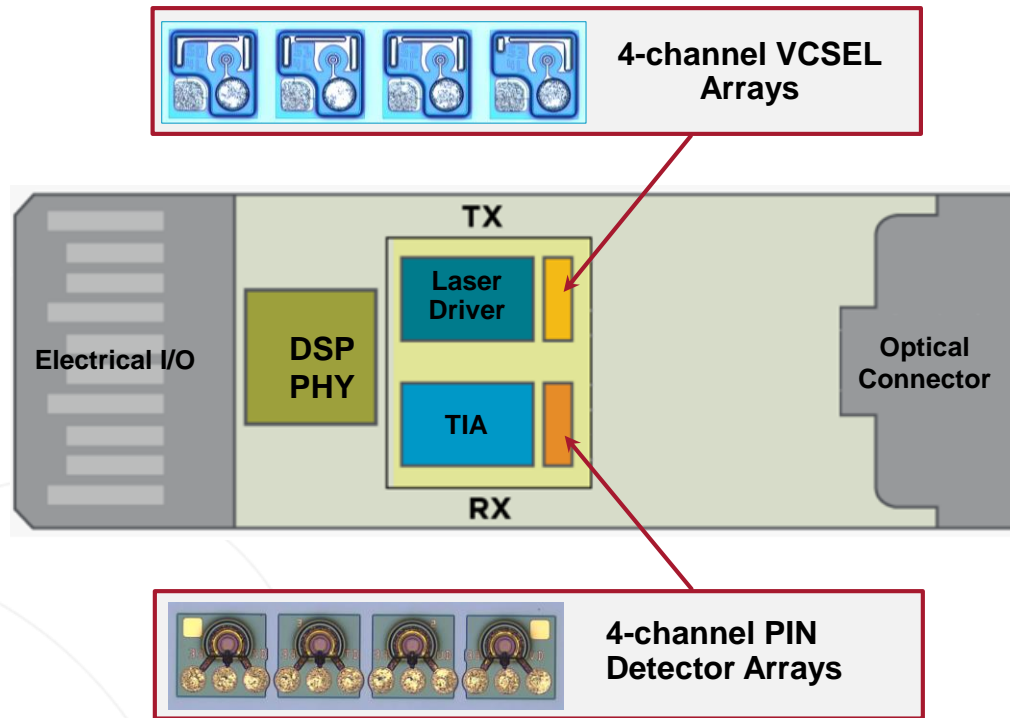
Single-mode, long reach



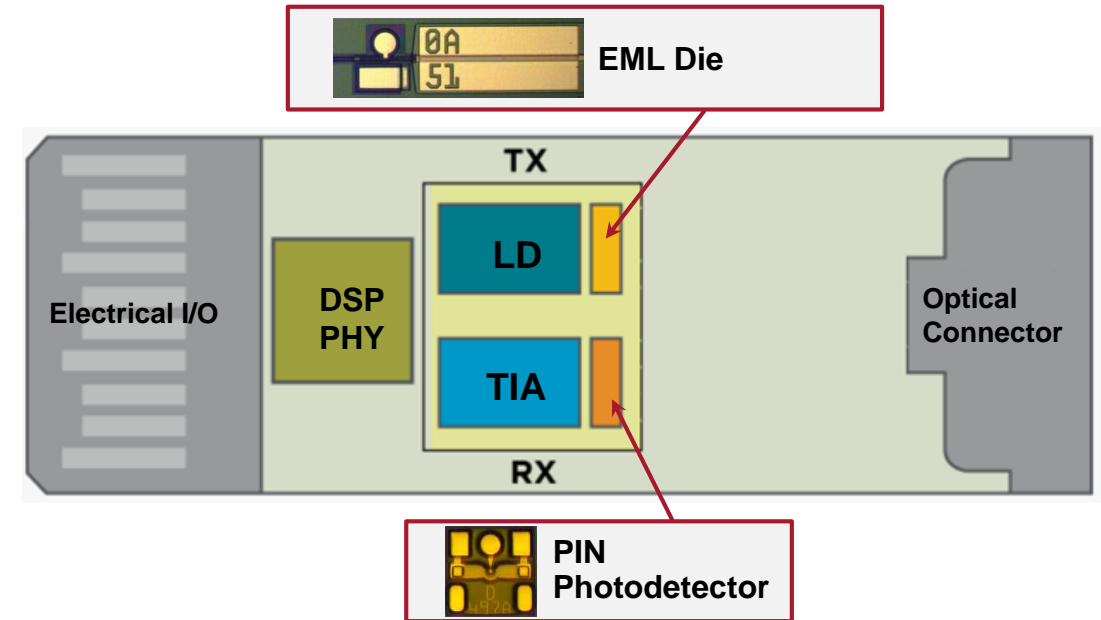
**CPO
(SiPho)**

Power and cost leadership

Broadcom Component Use Cases in AI Optical Transceivers



Multimode 800G and 1.6T VCSEL Based Transceivers



Singlemode 800G and 1.6T EML Based Transceiver

100G and 200G VCSELs



4x100G: Production Now
4x200G: 2H 2024 Samples

4x100G and 4x200G VCSEL Arrays

1.6T SR8 Transceiver Enablement

Up to 100m reach over Multi-Mode Fiber

Lowest Optical Transceiver Packaging Cost

Optimal for Back-End AI Network

100G and 200G EMLs



Production Now

100G and 200G Single Channel EMLs

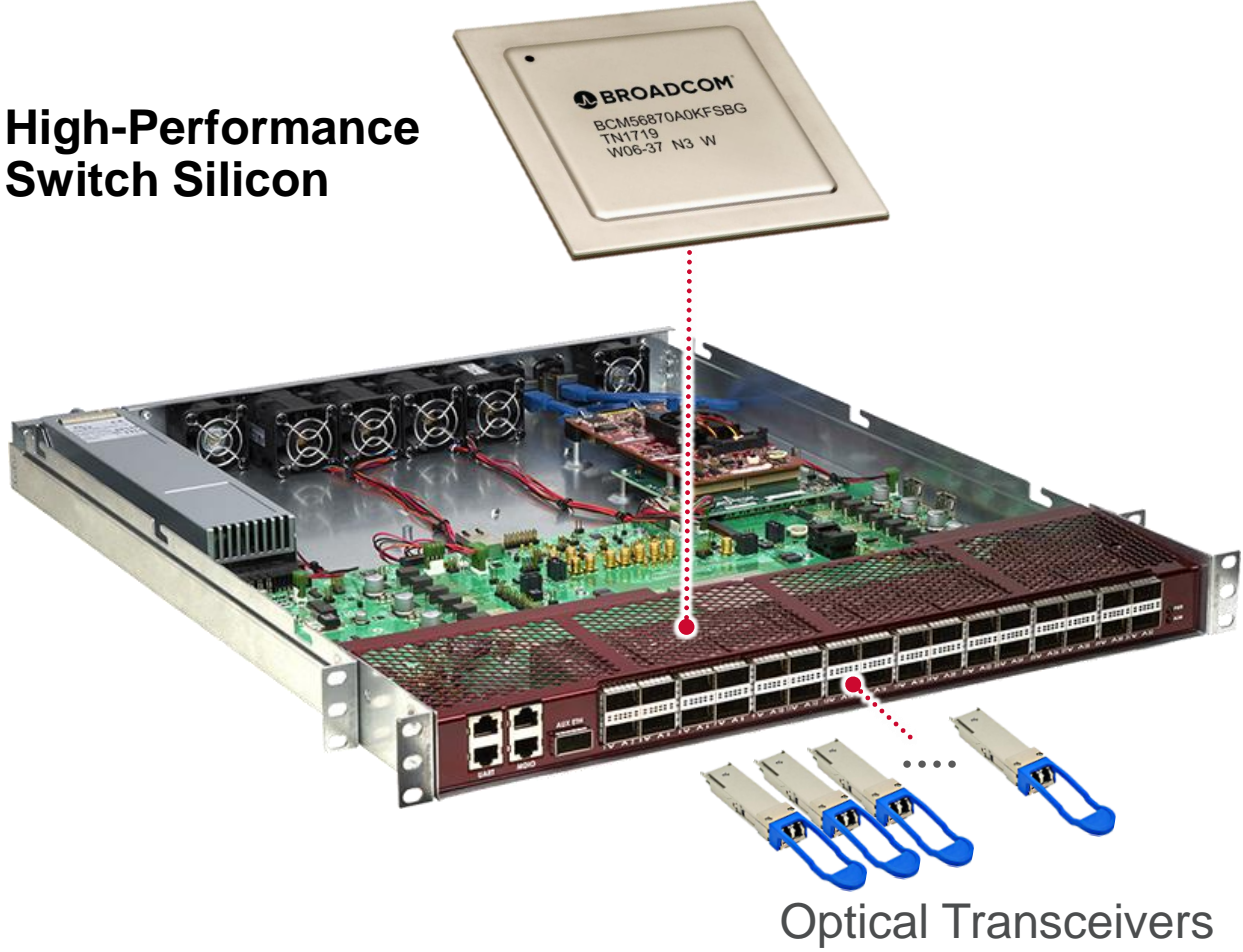
1.6T DR8 and CWDM8 Transceiver Enablement

Up to 2km reach over Single-Mode Fiber

WDM Enables Lowest Fiber Cost

Flexible Use for Back-End and Front-End Networks

Optical Interconnect Dominates Fabric Silicon Spend



Current Customer Spend*

10x\$

Switch

Optics

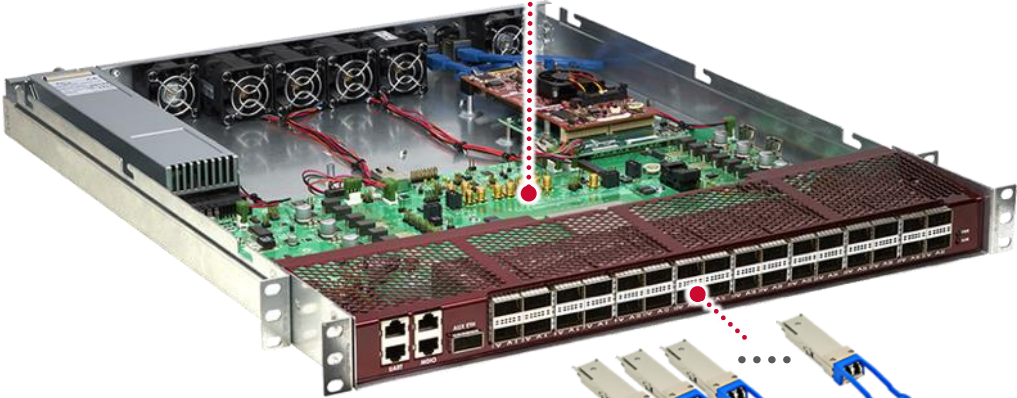
Opportunity for Step Function Improvement in Optical Connectivity

* Source: LightCounting, Dell'Oro, 650 Group and Broadcom internal estimates

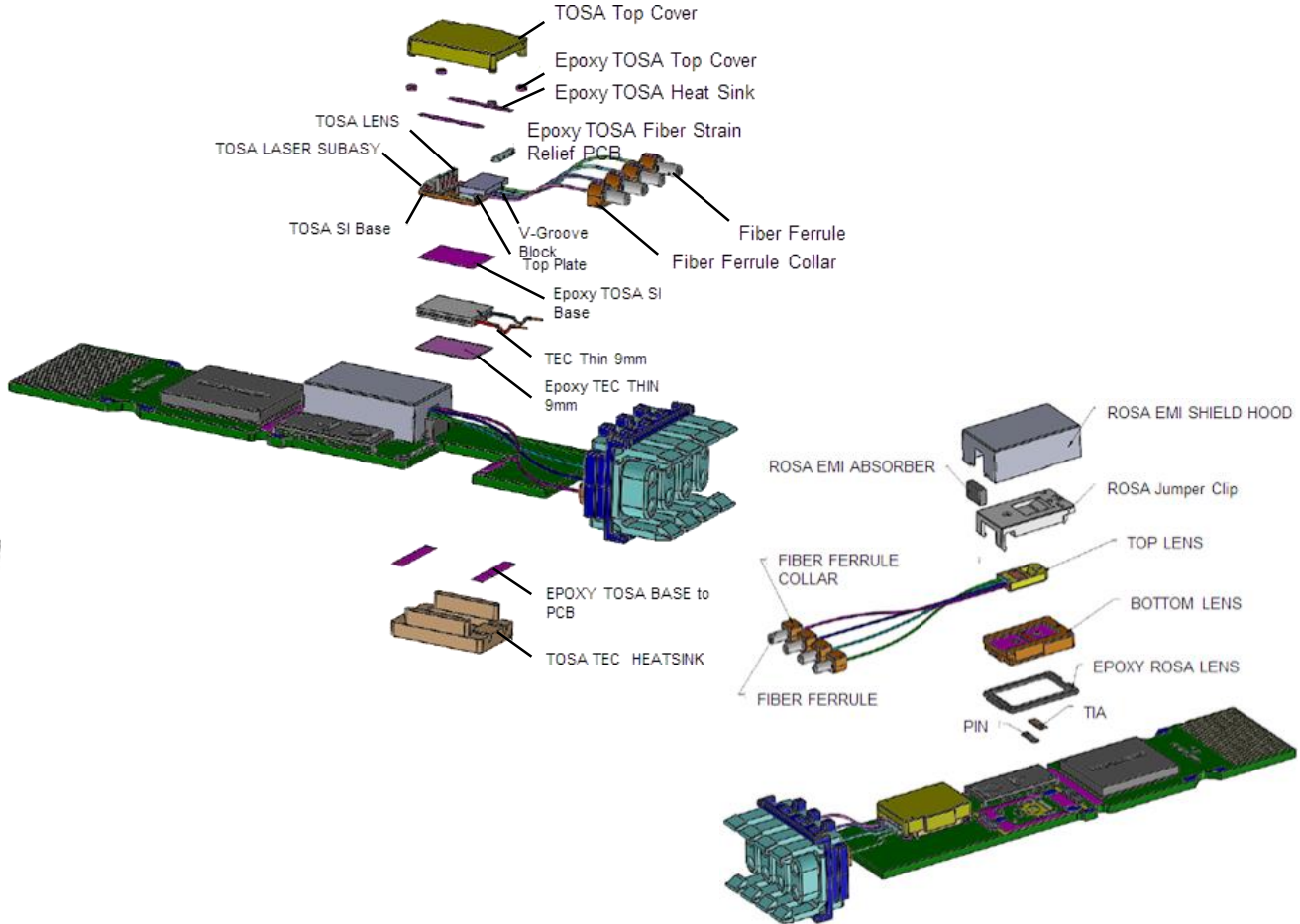


Complexity of Each Box in the Datacenter

High-Performance Switch Silicon



Optical Transceivers



Standard Rack Appliance

Standard Optical Transceiver

Evolution of Optics: Discrete III-V to Co-Packaged SiPh

Conventional Module Design

Labels in diagram: TOSA Top Cover, Epoxy TOSA Top Cover, Epoxy TOSA Heat Sink, TOSA LENS, Epoxy TOSA Fiber Strain Relief PCB, TOSA LASER SUBASY, V-Groove Back Top Plate, Fiber Ferrule, Fiber Ferrule Collar, TOSA SI Base, Epoxy TOSA SI Base, TEC Thin 9mm, Epoxy TEC THIN 9mm, ROSA EMI ABSORBER, ROSA EMI SHIELD HOOD, ROSA Jumper Clip, EPDXY TOSA BASE to PCB, TOSA TEC HEATSINK, TOP LENS, BOTTOM LENS, EPOXY ROSA LENS, FIBER FERRULE COLLAR, FIBER FERRULE, PIN, TIA.

Engineering and manufacturing limits to scale



Integrated Module Design Based w/ Silicon Photonics

SiPh Chiplets in Package (SCIP)

Labels in diagram: SiPh Chiplets in Package (SCIP), PHY IC, Fiber Jumper.

30% fewer Piece Parts!

Module Integration = First step to improved scale



Co-Packaged Optics

Highly Integrated Optical Engines (3.2T to 6.4T)

Why Co-Packaged Optics (CPO)?



Lowest Cost/Bit with massive reduction in components and interconnects



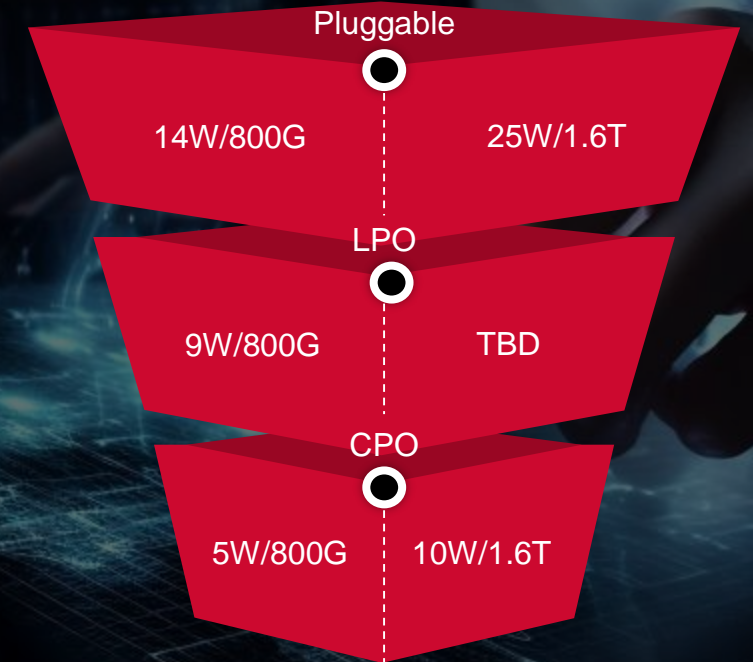
Power/Performance/Latency by eliminating the electrical interconnect power dissipation and variability



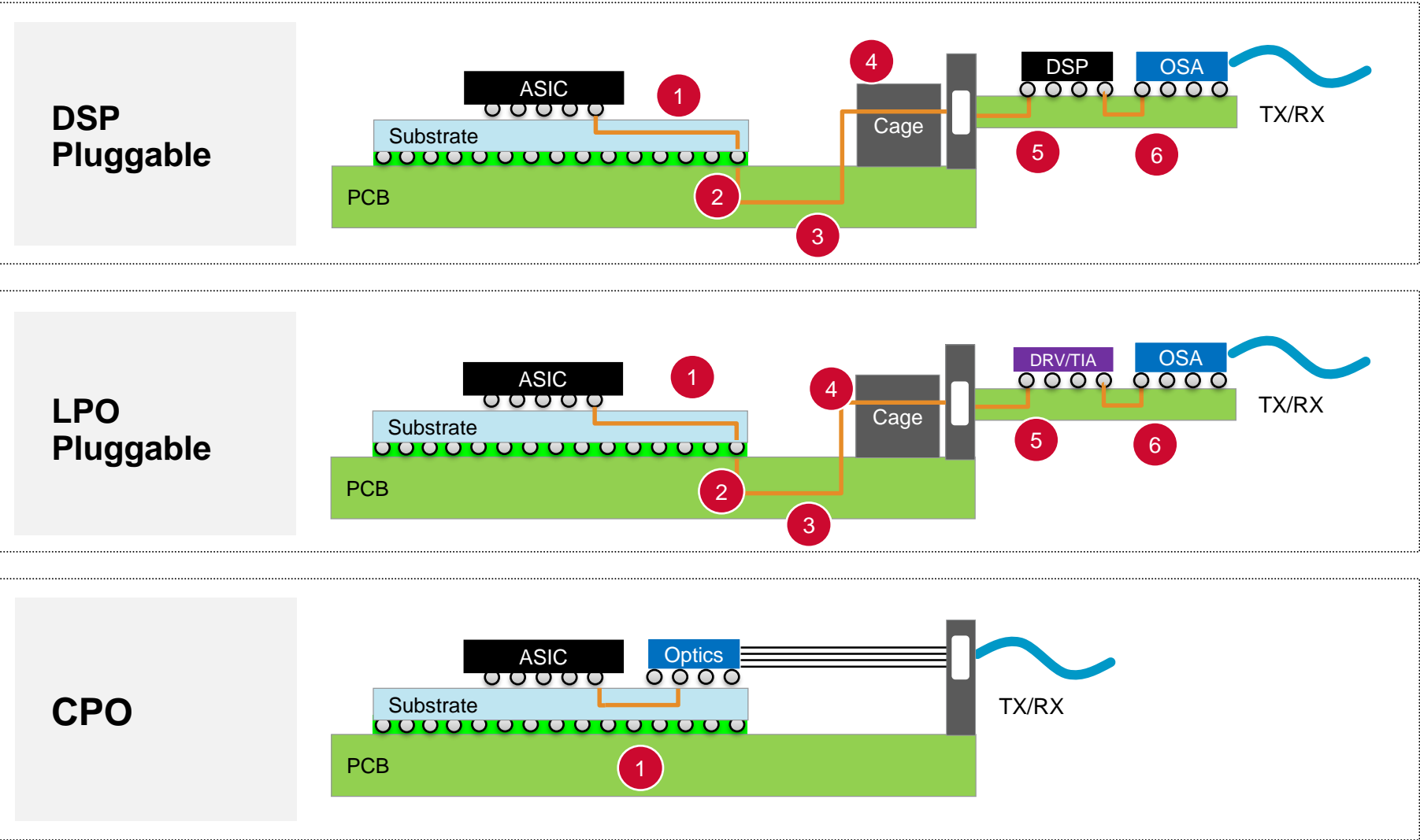
Leverage Silicon **Reliability** and eliminate practice of accepting high failure rate optics due to simple replacement

POWER COMPARISON

100G/lane ▼ 200G/lane



CPO Insertion Loss Savings vs. Pluggables



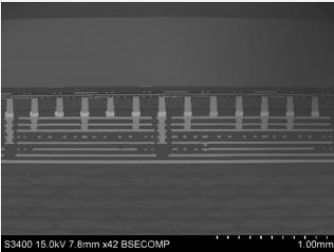
>30%
Cost Savings



>80%
Insertion Loss savings

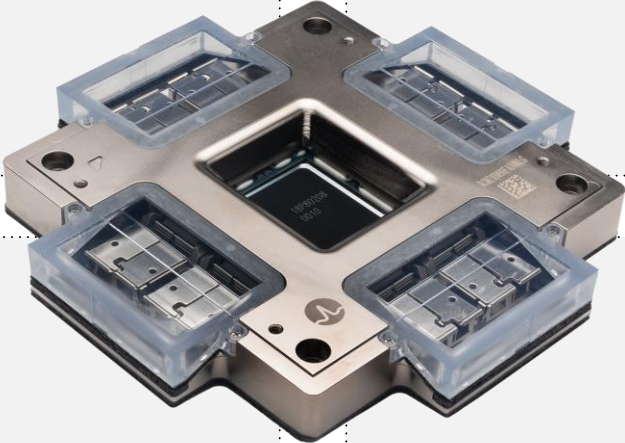
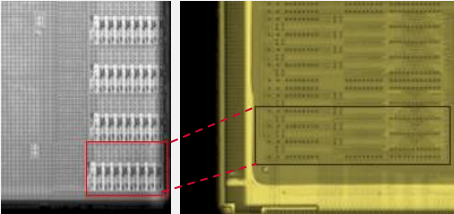
- 1 ASIC through substrate
- 2 Via Losses
- 3 PCB Trace Loss
- 4 Connector Losses
- 5 Module PCB Losses
- 6 OSA Interconnect loss

Sampling TH5-Bailly CPO today



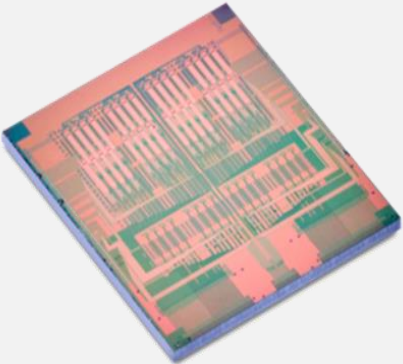
Advanced Packaging

64 channel EIC with CMOS driver and TIA



ODM System Integration

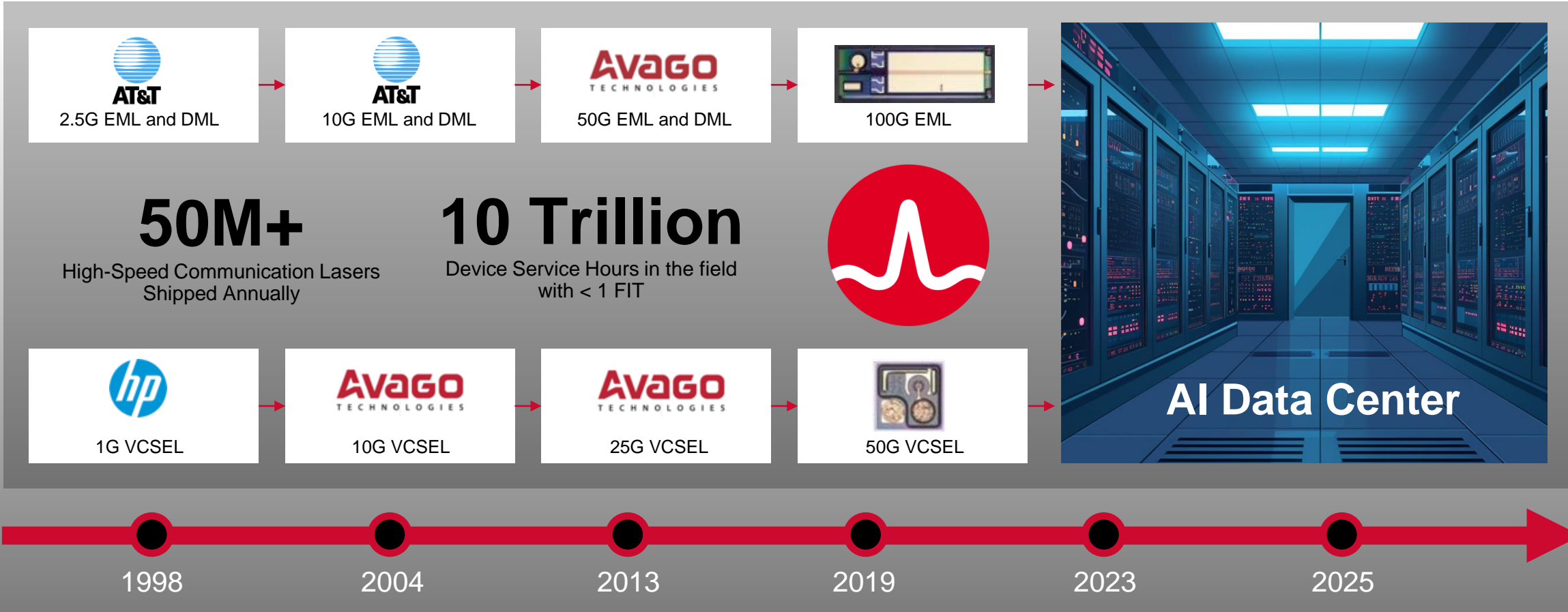
64 channel FR4 PIC with integrated mux/demux



Systems Shipping with Bailly CPO with Pluggable Lasers



The Broadcom Optics Advantage





Thank You





BROADCOM[®]

connecting everything[®]